

description

This device contains two independent positive-edge-triggered D-type flip-flops. A low level at the preset (PRE) or clear (CLR) input sets or resets the outputs regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup-time requirements are transferred to the outputs on the low-to-high transition of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the D input may be changed without affecting the levels at the outputs.

The 74ACT11074 is characterized for operation from –40°C to 85°C.

	FUNCTION TABLE									
	INP	NPUTS OUTPUTS								
PRE	CLR	CLK	D	Q	Q					
L	Н	Х	Х	Н	L					
н	L	Х	Х	L	Н					
L	L	х	Х	н†	H [†]					
н	Н	↑	н	н	L					
н	Н	\uparrow	L	L	Н					
н	н	L	Х	Q ₀	Q ₀					

[†] This configuration is <u>unstable</u>; that is, it does not persist when either PRE or CLR returns to its inactive (high) level.



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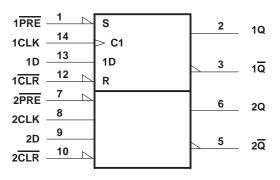
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74ACT11074 DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 6 V
Input voltage range, VI (see Note 1)	–0.5 V to V _{CC} + 0.5 V
Output voltage range, V _O (see Note 1)	–0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC})	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): D package	e 1.25 W
DB packag	ge 0.5 W
N package	e 1.1 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		0.8	V
VI	Input voltage	0	VCC	V
VO	Output voltage	0	VCC	V
ЮН	High-level output current		-24	mA
IOL	Low-level output current		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	ns/V
ТĄ	Operating free-air temperature	-40	85	°C



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vee	T _A = 25°C			MIN	MAY	UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	WIIN	WAX	UNIT
	1011 - 50 114	4.5 V	4.4			4.4		
	l _{OH} = -50 μA	5.5 V	5.4			5.4		
VOH	I _{OH} = -24 mA	4.5 V	3.94			3.8		V
	OH = -24 IIIA	5.5 V	4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
	101 - 50 - 4				0.1		0.1	
	I _{OL} = 50 μA	5.5 V			0.1		0.1	
VOL	lot = 24 mA	4.5 V			0.36		0.44	V
	I _{OL} = 24 mA	5.5 V			0.36		0.1	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
lj	$V_{I} = V_{CC}$ or GND	5.5 V			±0.1		±1	μΑ
ICC	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			4		40	μA
ΔI_{CC}^{\ddagger}	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V			0.9		1	mA
Ci	$V_I = V_{CC}$ or GND	5 V		3.5				pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡]This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended ranges of supply voltage and free-air temperature (unless otherwise noted) (see Figure 1)

			T _A = 2	25°C	MIN	МАХ	UNIT	
			MIN	MAX		WAA	UNIT	
fclock	Clock frequency		0	100	0	100	MHz	
L.	Pulse duration	PRE or CLR low	5		5			
tw		CLK low or high	5		5		ns	
		Data high or low	4.5		4.5			
t _{su} Set	Setup time before CLK1 PRE or CLR inactive	PRE or CLR inactive	2		2	ns		
t _h	Hold time after CLK↑		0		0		ns	

switching characteristics over recommended ranges of supply voltage and free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	ТО	T _A = 25°C			MIN	мах	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX		WAA	UNIT
fmax			100	125		100		MHz
^t PLH	PRE or CLR	Q or Q	1.5	5.7	8.9	1.5	9.6	ns
^t PHL	PRE OF CLR	QOIQ	1.5	6.6	11.3	1.5	12.5	115
tPLH	CLK	Q or Q	1.5	6	8.5	1.5	9.4	ns
^t PHL			1.5	5.7	8	1.5	8.8	115

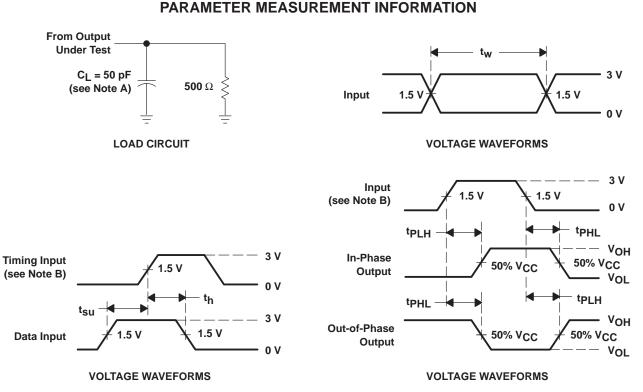
operating characteristics, V_CC = 5 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS		TYP	UNIT
Cpd	Power dissipation capacitance per flip-flop	CL = 50 pF,	f = 1 MHz	30	pF



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NOTES: A. CL includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r = 3 ns, t_f = 3 ns.

C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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